

**A HIGH PERFORMANCE INTERPOSER FOR A CHIP PACKAGE
USING DEFORMABLE BUTTON CONTACTS**

ABSTRACT OF THE DISCLOSURE

5 An interposer includes an array of buttons on a carrier having a
proximity to each other that allows contact between two adjacent buttons to
occur when at least one of the two adjacent buttons is axially compressed
above a predetermined threshold. The chip package includes a chip having a
first surface and a second surface, a printed circuit board having a first surface
10 and a second surface, and an interposer having an array of buttons between the
chip and the printed circuit board. The first surfaces are closer to each other
than the second surfaces.